

# **HD74HC182**

## Look-Ahead Carry Generator

REJ03D0586-0300 Rev.3.00 Jan 31, 2006

### **Description**

The HD74HC182 is a high-speed Carry Lockahead Generator. It is used with the HD74HC181 4-Bit Arithmetic Logic Unit to provide high-speed lockahead over World lengths of more than four bits. The device accepts up to four pairs of active-low Carry Propagate  $(\overline{P}_0, \overline{P}_1, \overline{P}_2, \overline{P}_3)$  and Carry Generate  $(\overline{G}_0, \overline{G}_1, \overline{G}_2, \overline{G}_3)$  signals and an active-high carries  $(C_{n+x}, C_{n+y}, C_{n+z})$  across four groups of binary adders. The HD74HC182 also has active-low Carry Propagate  $(\overline{P})$  and Carry Generate  $(\overline{G})$  outputs which may be used for further levels of lockahead.

The logic equations provided at the outputs are:

$$\begin{split} \overline{C_{n+x}} &= \overline{Y_0 \; (X_0 + C_n)} \\ \overline{C_{n+y}} &= \overline{Y_1 \; \{X_1 + Y_0 \; (X_0 + C_n)\}} \\ \overline{C_{n+z}} &= \overline{Y_2 \; [X_2 + Y_1 \; \{X_1 + Y_0 \; (X_0 + C_n)\}]} \\ Y &= Y_3 \; (X_3 + Y_2) \; (X_3 + X_2 + Y_1) \; (X_3 + X_2 + X_1 + Y_0) \\ X &= X_3 + X_2 + X_1 + X_0 \\ \text{or} \\ C_{n+x} &= G_0 + P_0 C_n \\ C_{n+y} &= G_1 + P_1 G_0 + P_1 P_0 C_n \\ C_{n+z} &= G_2 + P_2 G_1 + P_2 P_1 G_0 + P_2 P_1 P_0 C_n \\ \overline{G} &= \overline{G_3 + P_3 G_2 + P_3 P_2 G_1 + P_3 P_2 P_1 G_0} \\ \overline{P} &= \overline{P_3 P_2 P_1 P_0} \end{split}$$

Also, the HD74HC182 can be used with binary ALUs in an active-low or active-high input operand mode. The connections to and from the ALU to the carry lookahead generator are identical in both cases.

#### **Features**

• High Speed Operation:  $t_{pd}$  (Pn to P) = 11 ns typ ( $C_L = 50 \text{ pF}$ )

High Output Current: Fanout of 10 LSTTL Loads

• Wide Operating Voltage:  $V_{CC} = 2 \text{ to } 6 \text{ V}$ 

• Low Input Current: 1 μA max

Low Quiescent Supply Current: I<sub>CC</sub> (static) = 4 μA max (Ta = 25°C)

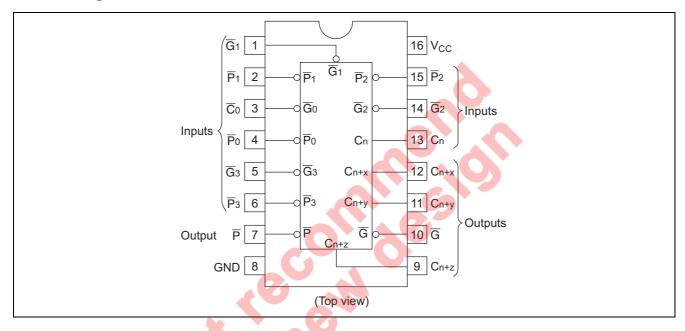
• Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HC182RPEL	SOP-16 pin (JEDEC)	PRDP0016DG-A (FP-16DNV)	RP	EL (2,500 pcs/reel)

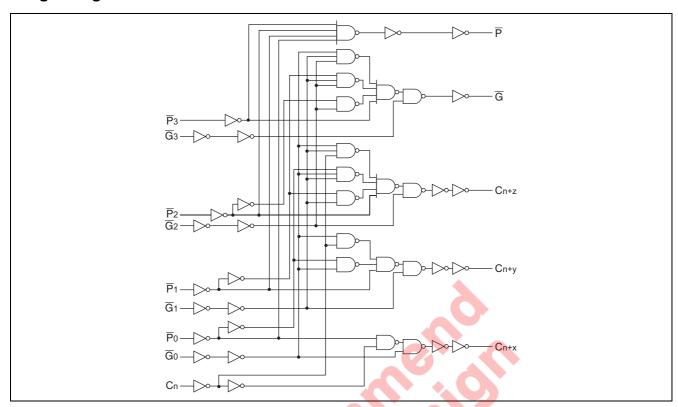
## **Function Table**

Item	Pin No.	Functions
$\overline{G}_0$ , $\overline{G}_1$ , $\overline{G}_2$ , $\overline{G}_3$	3, 1, 14, 5	Active-low carry generate inputs
$\overline{P}_0, \overline{P}_1, \overline{P}_2, \overline{P}_3$	4, 2, 15, 6	Active-low carry propagate inputs
C <sub>n</sub>	13	Carry input
$C_{n+x}, C_{n+y}, C_{n+z}$	12, 11, 9	Carry outputs
G	10	Active-low carry propagate output
P	7	Active-low carry propagate output
V <sub>CC</sub>	16	Supply voltage
GND	8	Ground

## **Pin Arrangement**



### **Logic Diagram**



## **Absolute Maximum Ratings**

Item	Symbol	Ratings	Unit
Supply voltage range	$V_{CC}$	-0.5 to 7.0	V
Input / Output voltage	Vin, Vout	–0.5 to V <sub>CC</sub> +0.5	V
Input / Output diode current	I <sub>IK</sub> , I <sub>OK</sub>	±20	mA
Output current	lo	±25	mA
V <sub>CC</sub> , GND current	I <sub>CC</sub> or I <sub>GND</sub>	±50	mA
Power dissipation	P <sub>T</sub>	500	mW
Storage temperature	Tstg	-65 to +150	°C

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

### **Recommended Operating Conditions**

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V <sub>CC</sub>	2 to 6	V	
Input / Output voltage	V <sub>IN</sub> , V <sub>OUT</sub>	0 to V <sub>CC</sub>	V	
Operating temperature	Та	-40 to 85	°C	
		0 to 1000		V <sub>CC</sub> = 2.0 V
Input rise / fall time*1	t <sub>r</sub> , t <sub>f</sub>	0 to 500	ns	V <sub>CC</sub> = 4.5 V
		0 to 400		$V_{CC} = 6.0 \text{ V}$

Note: 1. This item guarantees maximum limit when one input switches.

Waveform: Refer to test circuit of switching characteristics.

## **Electrical Characteristics**

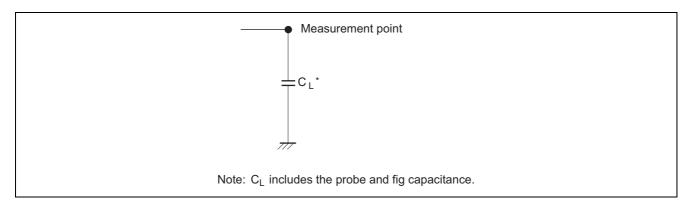
			Т	a = 25°	С	Ta = -40	to+85°C			
Item	Symbol	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit	Test Cor	nditions
Input voltage	V <sub>IH</sub>	2.0	1.5	_	_	1.5	_	V		
		4.5	3.15	_	_	3.15				
		6.0	4.2	_	_	4.2				
	$V_{IL}$	2.0	I	1	0.5	_	0.5	V		
		4.5		_	1.35		1.35			
		6.0		_	1.8	_	1.8			
Output voltage	V <sub>OH</sub>	2.0	1.9	2.0	_	1.9	_	V	$Vin = V_{IH} or V_{IL}$	$I_{OH} = -20 \mu A$
		4.5	4.4	4.5	_	4.4				
		6.0	5.9	6.0	_	5.9				
		4.5	4.18	_	_	4.13	_			$I_{OH} = -4 \text{ mA}$
		6.0	5.68	_	_	5.63				$I_{OH} = -5.2 \text{ mA}$
	V <sub>OL</sub>	2.0		0.0	0.1	_	0.1	V	$Vin = V_{IH} or V_{IL}$	$I_{OL} = 20 \mu A$
		4.5		0.0	0.1	_	0.1			
		6.0		0.0	0.1	_	0.1			
		4.5		_	0.26	_	0.33			$I_{OL} = 4 \text{ mA}$
		6.0		_	0.26		0.33			$I_{OL} = 5.2 \text{ mA}$
Input current	lin	6.0		_	±0.1	—	±1.0	μΑ	$Vin = V_{CC}$ or $GN$	D
Quiescent supply	Icc	6.0	_	_	4.0	_	40	μΑ	Vin = V <sub>CC</sub> or GN	D, $lout = 0 \mu A$
current								A		

## **Switching Characteristics**

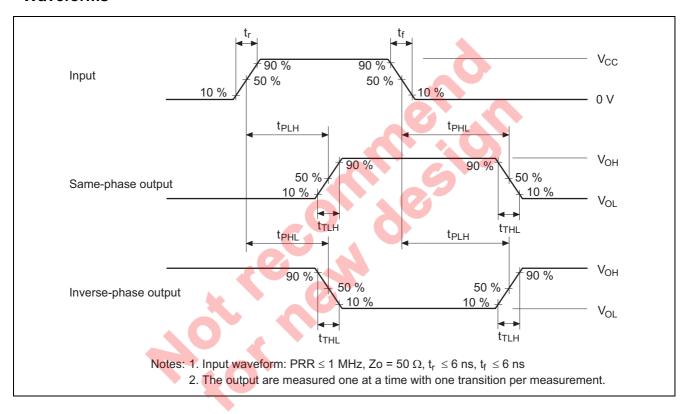
 $(C_L = 50 \text{ pF, Input } t_r = t_f = 6 \text{ ns})$ 

			Ta = 25°C Ta = -40 to +8		to +85°C				
Item	Symbol	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Propagation delay	t <sub>PLH</sub> , t <sub>PHL</sub>	2.0	_		140	_	175	ns	Pn to P
time		4.5	+	11	28		35		
		6.0		_	24	_	30		
		2.0	-		150	_	190	ns	Cn to output
		4.5	_	15	30	_	38		
		6.0	1		26	_	33		
		2.0	1	_	185	_	230	ns	Pn or Gn to output
		4.5		17	37	_	46		
	Ť	6.0		_	31	_	39		
Output rise/fall	t <sub>TLH</sub> , t <sub>THL</sub>	2.0	_	_	75	_	95	ns	
time		4.5		5	15	_	19		
		6.0		_	13	_	16		
Input capacitance	Cin	_	_	5	10	_	10	pF	

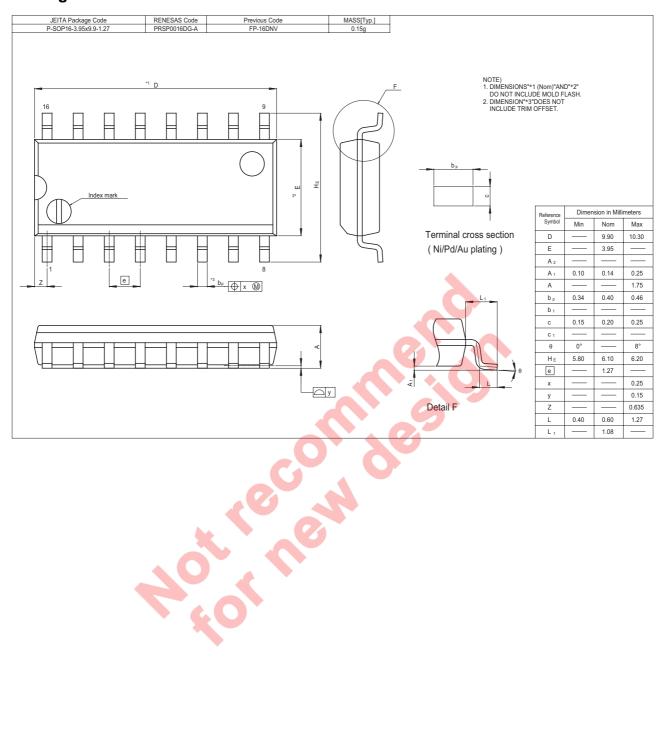
#### **Test Circuit**



#### **Waveforms**



#### **Package Dimensions**



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